

In the Specification:

Please replace paragraph [0003] with the following paragraph:

[0003] As the speed and complexity of processors and other integrated circuit components has increased, the need for high-speed input/output (I/O) and clean power delivery has also increased. Conventional packaging technologies are running into physical limitations ~~limitation~~, making them unable to meet all the requirements.

Please replace paragraph [0008] with the following paragraph:

[0008] Generally, current technology has all I/O and power going through the pins or pads on the CPU package. In some high-end implementations, such as in server computers, an additional power connector on the edge of the CPU substrate may be utilized. This approach also raises inductance, which in turn can degrade the signals significantly.

Please replace paragraph [0020] with the following paragraph:

[0020] Fig. 2 illustrates an exemplary block diagram of a computer system 200 in accordance with an embodiment of the present invention. The computer system 200 includes a central processing unit (CPU) 202 coupled to a bus 205. In one embodiment, the CPU 202 is a processor in the Pentium® family of processors including the Pentium® II processor family, Pentium® III processors, Pentium® IV processors available from Intel Corporation of Santa Clara, California. Alternatively, other CPUs may be used, such as Intel's XScale

processor, Intel's Banias Processors, ARM processors available from ARM Ltd. of Cambridge, the United Kingdom, or OMAP processor (an enhanced ARM-based processor) available from Texas Instruments, Inc., of Dallas, Texas.

Please replace paragraph [0026] with the following paragraph:

[0026] Fig. 3 illustrates an exemplary top view of a socket 300 in accordance with an embodiment of the present invention. The socket 300 includes an actuation lever 302 (e.g., to lock down or hold in place an inserted component), a socket grid 304 (e.g., to receive pins of the inserted component), a socket frame 306 (e.g., to provide structural rigidity for the socket 300), a cable connector 308 (e.g., to receive a flex cable or other types of cables), and a cable 310.

Please replace paragraph [0027] with the following paragraph:

[0027] In an embodiment of the present invention, the cable 310 may be any type of cable such as a ribbon cable, flex cable, flat cable, combinations thereof, and the like. The signals (such as I/O signals) routed through the cable may then be coupled through the cable connect to the socket 300. These signals may be coupled to individual receptacles within the socket grid 304 and/or coupled to one or more of the power/ground planes. In one embodiment of the present invention, the power/ground plane may be provided through the socket 300 (e.g., through its frame 306). Moreover, the signals and/or power/ground may be coupled to the motherboard through the socket 300 (e.g., through its frame 306).

Please replace paragraph [0031] with the following paragraph:

[0031] Fig. 5 illustrates an exemplary side view of a chip-to-chip coupling system 500 in accordance with an embodiment of the present invention. The system 500 includes a motherboard 502, a chipset 504, an integrated socket 506, a chip 508 (such as a CPU discussed with respect to other figures herein, e.g., 202 of Fig. 2), the cable 310, the connector 308, and the socket 300. As illustrated in Fig. 5, the cable 310 may couple the chipset 504 (e.g., through the connector 308) to the integrated socket 506. In turn, the integrated socket may provide connections between the cable 310 and one or more of power/ground planes and/or signals (e.g., ~~I/O~~ I/O signals) and the chip 508 and/or the motherboard- 502.

Please replace paragraph [0041] with the following paragraph:

[0041] Fig. 9 illustrates an exemplary ~~integrates~~ integrated socket 900 in accordance with an embodiment of the present invention. In one embodiment of the present invention, the integrated socket 900 may have characteristics that are the same or similar to those discussed with respect to the integrated socket 506. The integrated socket 900 includes the actuation lever 302, the socket grid 304, and the socket frame 306. The integrated socket 900 may further include a cable latch or lid 902, which may snap down to connect the cable 310 to the integrated socket 900.

Please replace paragraph [0043] with the following paragraph:

[0043] In one embodiment of the present invention, the integrated socket/connectors discussed herein may enable the separation of strategic I/O and/or power from the board. In another embodiment of the present invention, since flex cable may generally have much better and consistent capacitance, the techniques discussed herein may allow for cleaner signal linking to support chipsets and/or smart voltage regulators. In an alternate embodiment of the present invention, the socket may also include holes for mounting purposes (e.g., mounting on the motherboard).

Please replace paragraph [0044] with the following paragraph:

[0044] In a further embodiment of the present invention, a single multipurpose connector is utilized to electrically connect components to enable transfer of power/ground and/or I/O into and out of logic circuits. In yet a further embodiment of the present invention, the integrated sockets discussed herein yield low inductance, low resistance, and low cost sockets and connector combinations that reduce part count, motherboard footprint, cross talk, and/or inductance on selected power/ground and/or I/O lines.